

Pinning

Descriptions

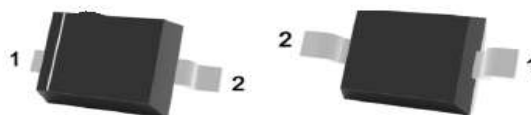
Schottky Diode in a SOD-323 Plastic Package.

Features

Schottky diodes, Qualified to AEC-Q101
Standards for High Reliability, HF Product.

Applications

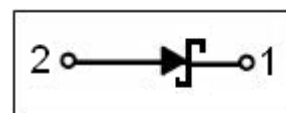
Small signal diode, Meet the stringent
requirements of automotive applications.



PIN1:Cathode

PIN2:Anode

Equivalent Circuit



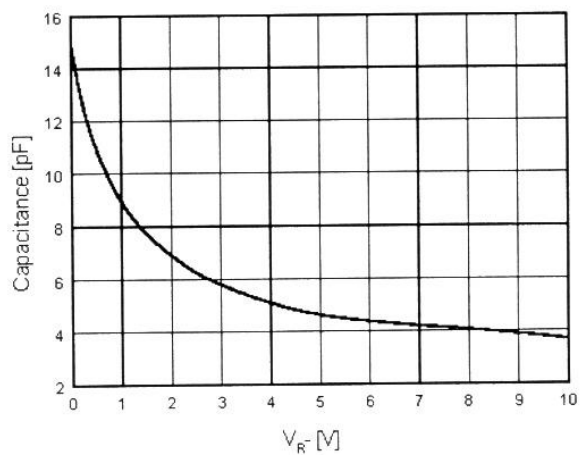
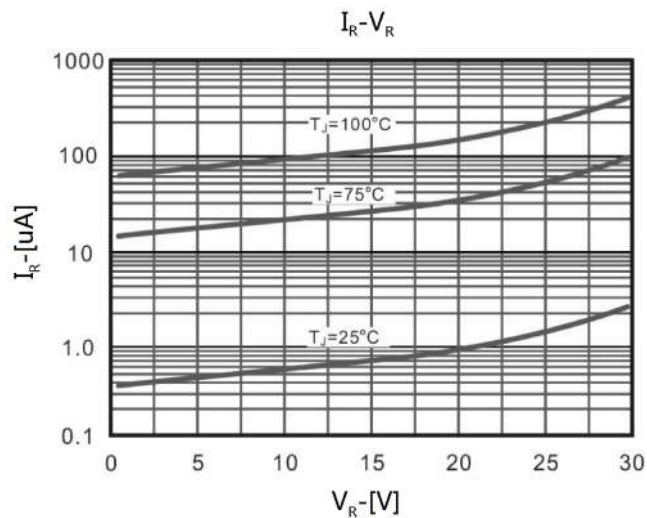
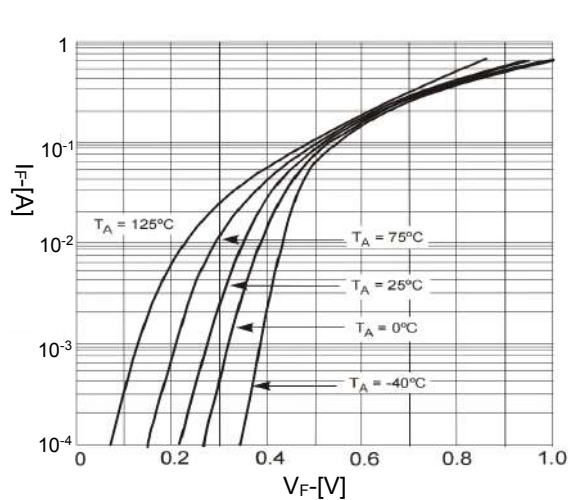
Absolute Maximum Ratings(Ta=25°C)

Parameter	Symbol	Rating	Unit
Repetitive peak reverse voltage	V_{RRM}	30	V
Continuous forward current	I_F	200	mA
Surge non repetitive forward current	I_{FSM}	600	mA
Power Dissipation	P_D	250	mW
Typical Thermal Resistance Junction to Ambient	$R_{\theta JA}$	430	°C/W
Junction Temperature Range	T_J	125	°C
Storage Temperature Range	T_{stg}	-55~150	°C

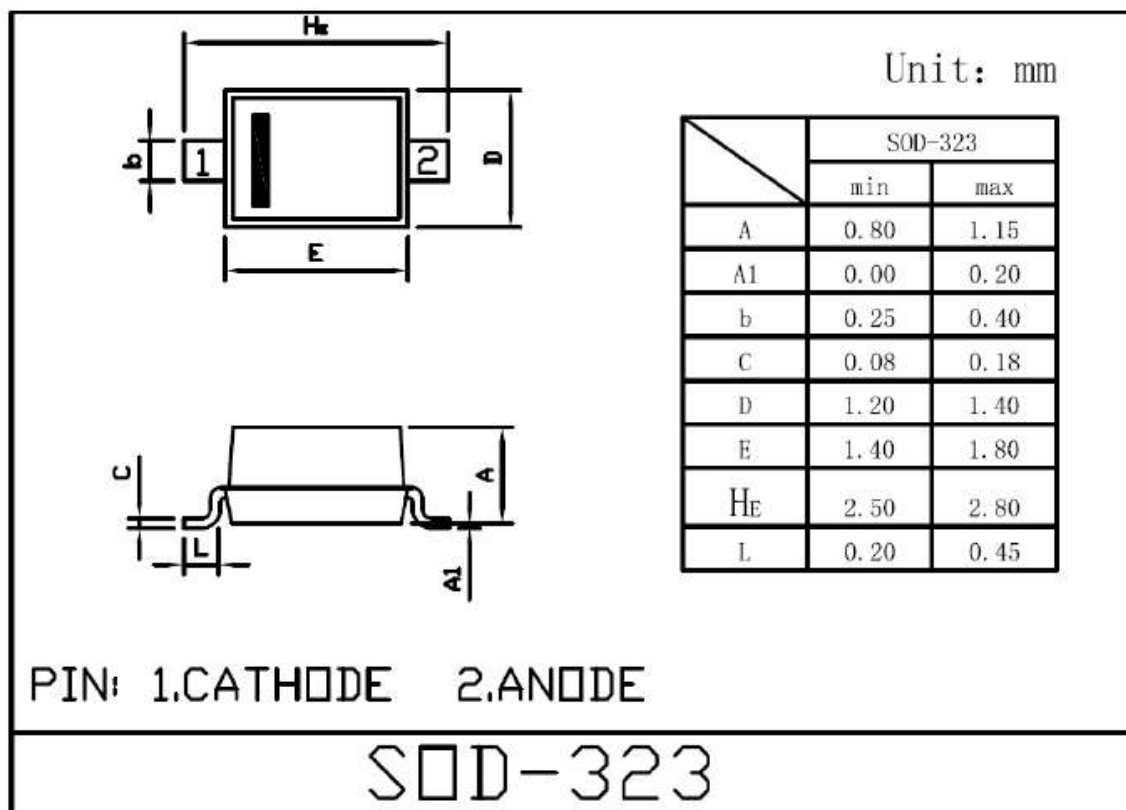
Electrical Characteristics(Ta=25°C)

Parameter	Symbol	Test Conditions	Rating		Unit
			MIN		
Reverse Voltage	V_R	$I_R=10\mu A$	30		V
Peak Forward voltage	V_F	$I_F=0.1mA$		240	mV
		$I_F=1.0mA$		320	mV
		$I_F=10mA$		400	mV
		$I_F=30mA$		500	mV
		$I_F=100mA$		0.8	V
Instantaneous Reverse Current	I_R	$V_R=25V$		2.0	μA
Total capacitance	C_T	$V_R=1.0V$ $f=1.0MHz$		10	pF
Reverse recovery time	t_{rr}	$I_{RR}=1.0mA$ $R_L=100\Omega$ $I_F=1R=10mA$		5.0	ns

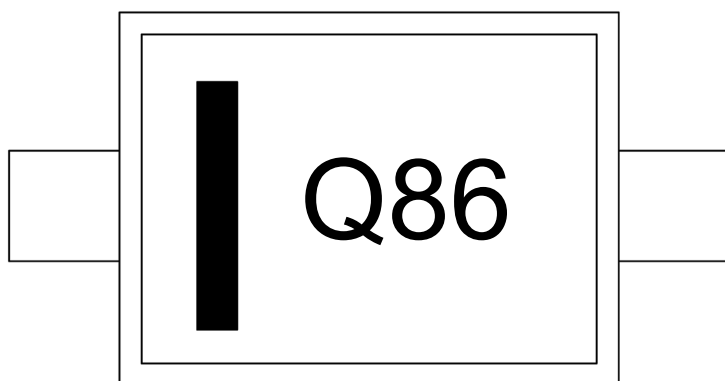
Electrical Characteristic Curve



Package Dimensions



Marking Instructions

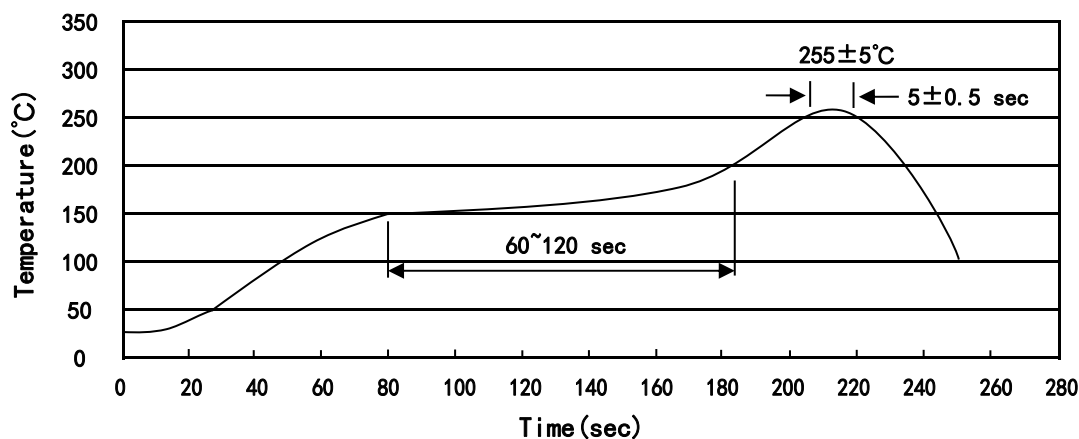


Note:

Q: Automobile halogen-free product Code

86: Product Type Code

Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- 1.Preheating:150~200°C, Time:60~120sec.
- 2.Peak Temp.:255±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

Resistance to Soldering Heat Test

ConditionsTemp.:260±5°C Time:10±1 sec

Packaging SPEC.

Package Type	Units					Dimension (unit : mm3)		
	Units/Reel	Reels/Inner Box	Units/Inner Box	Inner Boxes/Outer Box	Units/Outer Box	Reel	Inner Box	Outer Box
SOD-323	3,000	10	30,000	6	180,000	7" x8	180×120×180	390×385×205